## LISTING SHOWING THE AMENDMENT TO THE CLAIMS

This listing replaces all prior listings of claims.

## IN THE CLAIMS

Amend the claims as follows:

- 1 (Original). A polymer mixture, the polymer mixture having semiconductive properties, the mixture comprising: and
  - one or more semiconductive polymers; -and
  - one or more non-semiconductive polymers being present in the polymer mixture.
- 2 (Original). The polymer mixture as claimed in claim 1 wherein, characterized in that the semiconductive polymer/ the semiconductive polymers include at least one of the group consisting of is/are polythiophene, polyfluorene and/or polythienylenevinylene.
- 3 (Currently amended). The polymer mixture as claimed in <u>claim 1</u> <u>wherein either</u> of the preceding claims, characterized in that the non—semiconductive polymer/the non-semiconductive polymers is/are are selected from the group consisting of at <u>least one of polystyrene</u>, polymethyl methacrylate, cymel and/or poly isobutyl.
- 4 (Currently amended). The polymer mixture as claimed in <u>claim 1 including any of</u> the preceding claims, characterized in that it contains solvents <u>including at least one</u> of, in particular chloroform, toluene, ketones, dioxane and/or heptane.
- 5 (Currently amended).. The polymer mixture as claimed in <u>claim 1 wherein any of</u> the <u>preceding claims</u>, <u>characterized in that</u> it additionally contains molecules which

are smaller than polymers, in particular oligomers, conductive molecules and/or semiconductive molecules.

- 6 (Currently amended). The polymer mixture as claimed in <u>claim 1 wherein any of</u>
  the <u>preceding claims</u>, <u>characterized in that</u> it <u>further includes</u> <u>-consists</u> of <u>said</u>
  substances and customary additives.
- 7 (Currently amended). The polymer mixture as claimed in <u>claim 1 wherein any of</u> the preceding claims, characterized in that it has a viscosity of more than 8 mpa.s, in particular of more than 80 mPa.s.
- 8 (Currently amended). A printing process for the production of a semiconductive double layer by a known process, selected from—such as the group consisting of at least one of the screen printing, flexographic printing, offset printing, gravure printing and/or pad printing process, the a polymer mixture as claimed in claim 1 any of the preceding claims being used as a print medium in the known process.
- 9 (Currently amended). A printing process for the production of a semiconductive double layer by a known process, selected from such as the group consisting of the screen printing, flexographic printing, offset printing, gravure printing and/or pad printing process, the double layer produced by printing the printing medium containing
  - one or more semiconductive polymers in a first of one of its layers,
  - one or more non-semiconductive polymers in <u>a second of its-other layers</u>.
- 10 (Currently amended). The printing process for the production of a double layer

as claimed in claim 9, in which a polymer mixture as claimed in any of claims 1 to 7 is used.

11 (Currently amended). An electronic component, in particular circuit, which is produced using a polymer mixture as claimed in claim 1 any of claims 1 to 7 and/or has a double layer as claimed in claim 9.

## Add the following claims:

- 12 (new). An electronic component which is produced using a polymer mixture that forms a double layer as claimed in claim 9.
- 13. (new). An electronic component which is produced using a polymer mixture as claimed in claim 2.
- 14. (new). An electronic component which is produced using a polymer mixture as claimed in claim 3.
- 15 (new). An electronic component which is produced using a polymer mixture as claimed in claim 4.
- 16. (new). An electronic component which is produced using a polymer mixture as claimed in claim 5.
- 17. (new). An electronic component which is produced using a polymer mixture as claimed in claim 6.

18. (new). An electronic component which is produced using a polymer mixture as claimed in claim 7.

19 (new) The printing process for the production of a double layer as claimed in claim 9, in which a polymer mixture as claimed in claim 2 is used.

20 (new) The printing process for the production of a double layer as claimed in claim 9, in which a polymer mixture as claimed in claim 3 is used.